



Designed for Solution
Engineered to Last



ELECTRIC CONVECTION

Applications

- This type of furnace is widely used in SMD element reflow soldering, chip joining, etc.
- Epoxy curing, encapsulation, underfill curing, chip joining and die bonding.

Highlights

- 400°C Maximum Temperature Rating
- $\pm 1^\circ\text{C}$ PID Control Precision
- High Quality Electric Heating Wires
- Forced Air Cooling
- $\pm 2^\circ\text{C}$ Cross Belt Uniformity
- Alternative IR Heating Method
- Independent Over Temperature Control in Each Zone
- Belt Speed Control
- Free Shipping and Delivery
- Custom Voltage Configurations